### WAQ7F SERIES

#### 1. PART NO. EXPRESSION :

<u>WAQ 7 F 510 - R B - 10</u> (a) (b)(c) (d) (e)(f) (g) (a) Series code (b) Dimension code (c) Material code (d) Inductance code : 510 = 51 uH (e) R : Tape & Reel (f) Rated Current : B = 200mA (g) 10 : Internal Control Number

### 2. CONFIGURATION & DIMENSIONS :









PCB Pattern

PC board should be designed so that products are not sufficient under mechanical stress as warping the board. Products shall be positioned in the sideway direction against the mechanical stress to prevent failure.

A	В	С	D1	D2	L	Н	K1	K2	G1	G2
4.5±0.2	3.2±0.2	2.8±0.2	1.0±0.1	1.2±0.1	5.2	3.6	0.85	0.7	3	0.9

#### 3. SCHEMATIC :

#### Common mode



#### 4. MATERIALS :



#### Differential mode



(a) Upper Plate:Ferrite

- (b) Core: Ferrite Core
- (c) Termination : Tin (Pb Free)

(d) Wire : Enameled Copper Wire

NOTE : Specifications subject to change without notice. Please check our website for latest information.



iant

01.04.2015

2015

01

 $\mathbf{PT}$ Έ PR

**CONTROLLED COPU 1** 

### WAQ7F SERIES

#### 5. GENERAL SPECIFICATION :

- a) Test Frequency: Inductance:100KHz/0.1V; Impedance:10MHz/0.1V
- b) Operating temperature: -40  $^\circ\!\mathrm{C}$  ~+125  $^\circ\!\mathrm{C}$
- c) Storage Temperature:-40℃ ~ +125℃
- d) All test data is referenced to  $25^\circ\!\mathrm{C}$  ambient.
- e) Indicate Compliant to AEC-Q200 and PPAP level4 eligibility

#### 6. ELECTRICAL CHARACTERISTICS :

Part No.	Common mode Inductance ( uH )	DCR (Ω) Max.	Rated Current (mA)	Rated Voltage ( Vdc )	IR (Ω) Min.
WAQ7F110-RB-10	11+50/-30%	0.8	200	50	10M
WAQ7F510-RB-10	51+50/-30%	1.0	200	50	10M
WAQ7F101-RA-10	100+50/-30%	2.0	100	50	10M

#### 7. CHARACTERISTICS CURVES :







NOTE : Specifications subject to change without notice. Please check our website for latest information.

SUPERWORLD ELECTRONICS (S)

Pb Rolls Compliant

Proprietary and Confidential Property of Superworld



WAQ7F SERIES

### 8. RELIABILITY & TEST CONDITION :

ITEM	PERFORMANCE	TEST CONDITION		
Electrical Characteristics Test				
Z (common mode)		Agilent-4291A+ Agilent-16197A		
DCR	Refer to standard electrical characteristics list	Agilent-4338B		
I.R.		Agilent4339		
Temperature Rise Test	Rated Current < 1A $\Delta T 20^{\circ}$ CMax Rated Current $\geq$ 1A $\Delta T 40^{\circ}$ CMax	<ol> <li>Applied the allowed DC current.</li> <li>Temperature measured by digital surface thermometer.</li> </ol>		
Mechanical Performance Test	t in the second s			
Solderability Test	More than 90% of termincal electrode should be covered with solder.	Preheat: 150°C ,60sec Solder: Sn99.5%-Cu0.5%. Temperature: 245±5°C . Flux for lead free: Rosin.9.5%. Dip time: 4±1sec. Depth: completely cover the termination		
Solder Heat Resistance	Appearance: No damage. Inductance: within±10% of initial value	Solder tamperature: 260± 5° C Temperature ramp/immersion and immersion rate: 25± 6 mm/s Dip time: 10± 1sec. Number of heat cycles:1 Depth: completely cover the termination.		
Terminal Strength	RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning : Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a force (>0805:1kg, <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.		



WAQ7F SERIES

#### 8. RELIABILITY & TEST CONDITION :

ITEM	PERFORMANCE		TEST CONDIT	TON	
Reliabilty Test					
Life Test		Preconditioni (IPC/JEDEC Temperature Applied Curre Duration : 100 Measured at r	ng: Run through IR refit J-STD-020D Classificati 85± 2° C nt : rated current I0± 12hrs oom temperature after	ow for 2 times. fon Reflow Profiles) placing for 24±2 hrs	6.
Thermal Shock	Appearance: No damage.	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles)			
	Inductance: within±10% of initial value	Step	Temperature (° C)	Times (min.)	
	RDC: within ±15% of initial value and shall not	1	-40±2	30±5	- 9
	exceed the specification value	2	25±2	≦ 0.5	0
		3	105±2	30±5	2
		Number of cy Measured at	cles: 500 room fempraturc after p	placing for 24±2 hrs	00
Humidity Resistance Test		Preconditioni (IPC/JEDEC Temperature Humidity : 85 Duration: 10 Measured at	ng: Run through IR reflo J-STD-020D Classificati : 85±2° C ±2% R.H 00hrs Min. with 100% r room temperature after	ow for 2 times. fon Reflow Profiles) ated current placing for 24±2 hrs	s bertv of S
Vibration Test		Preconditioni (IPC/JEDEC	ng: Run through IR reflo J-STD-020D Classificati	ow for 2 times. on Reflow Profiles)	- Droi
		Oscillation Fi Equipment : \ Total Amplitu Testing Time orientations)。	requency : 10~2K~10 /ibration checker de : 1.52mm±10% : 12 hours(20 minutes,	Hz for 20 minutes 12 cycles each of 3	identia
					UO (
					anc
					2
					<u>n</u>
					<u>D</u> .
					Q
					Ω



PR

**CONTROLLED COPY 4** 

2015

01

NOTE : Specifications subject to change without notice. Please check our website for latest information.

SUPERWORLD ELECTRONICS (S) PTE

## 9. SOLDERING AND MOUNTING :

#### 9-1. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems.

If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### 9-1.1 Solder Re-flow :

Recommended temperature profiles for re-flow soldering in Figure 1.

#### 9-1.2 Soldering Iron (Figure 2) :

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Note : a) Preheat circuit and products to 150° C.
  - b) 355° C tip temperature (max)
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm

WAQ7F SERIES

- c) Never contact the ceramic with the iron tip f)
- f) Limit soldering time to 4-5 secs.







Iron Soldering times: 1 times max. Fig.2



WAQ7F SERIES

### 10. PACKAGING INFORMATION :







Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 12mm	13.5±0.5	60.0±2.0	13.5±0.5	178.0±2.0

#### 10-2 Tape Dimension / 12mm



	-	-	-		-
Series	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
WAQ7F	4.90±0.1	3.60±0.1	3.00±0.1	8.0±0.1	0.26± 0.05

#### 10-3. Packing Quantity

Series	WAQ7F	
Chip / Reel	500	
Inner Box	2500	
Middle Box	12500	
Carton	25000	



WAQ7F SERIES





The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(° C)	(%)	(hPa)	(mm/min)
5~35	45~85	860~1060	

### **Application Notice**

- 1. Storage Conditions :
  - To maintain the solderability of terminal electrodes :
    - a) Temperature and humidity conditions : Less than 40° C and 60% RH.
    - b) Recommended products should be used within 12 months from the time of delivery.
    - c) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation :

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

